

IN THE SPECIFICATION:

Please amend paragraph [0042] as follows:

[0042] With reference to FIG. 6b, a third embodiment of the mounting element 13" includes clips 24" and 28", which extend over major surfaces of semiconductor device 12. Each of clips 24" and 28" has an alignment device receiving end 27" (not shown) and 31", respectively, which is adapted to engage a corresponding receiving mechanism ~~on the~~ on alignment ~~device~~ device 40' (shown in FIG. 9).

Please amend paragraph [0043] as follows:

[0043] FIGs. 7 and 8 show an alignment device 40, which is an elongate member including a body which defines an elongated interconnection receptacle 41 formed in the top surface thereof and extending downwardly therein. Interconnection receptacle 41 has an upper end 42, which receives a semiconductor device 12 (*see* FIG. 1), and a lower end 43. Lower end 43 includes contacts 44 therein. As alignment device 40 is mounted to carrier substrate 60, ~~the contacts~~ contacts 44 are electrically connected to their corresponding terminals 61 on carrier substrate 60.

Please amend paragraph [0046] as follows:

[0046] A spring arm 47, located between terminal contact end 45 and bond pad contact end 46, facilitates movement of the bond pad contact end relative to the substrate contact end as a semiconductor device ~~12~~ package 10 (*see* FIG. 1) is inserted into interconnection receptacle 41. Preferably, while subjected to a bending force, spring arm 47 exerts an opposite reactive (i.e., spring) force, such that bond pad contact end 46 snugly abuts its corresponding bond pad 19 (*see* FIGs. 2 and 3). Thus, spring arm 47 creates an interference contact between contact 44 and bond pad 19 (*see* FIGs. 2 and 3).

Please amend paragraph [0047] as follows:

[0047] Preferably, the end of bond pad contact end 46 is bent outwardly to form an outward extension 48. Outward extension 48 facilitates movement of bond pad contact end 46 as

a semiconductor device ~~12~~ package 10 (*see* FIG. 1) is inserted into interconnection receptacle 41. Preferably, the shape of outward extension 48 also prevents damage to semiconductor device 12 during its insertion into interconnection receptacle 41.

Please amend paragraph [0048] as follows:

[0048] Contacts 44 have a length of about 1½ mm (about 60 mils) or less. More preferably, contacts 44 are about 1 mm (about 40 mils) long or shorter. As those in the art are aware, longer contacts create greater inductance. Thus, less parasitic inductance and capacitance are generated by shorter contacts 44. The total length of contacts 44 depends on the thickness of the base of the alignment device, the circuit length required to establish an electrical connection with terminal 61 on carrier substrate 60 (*see* ~~FIG. 7~~, FIG. 8), and the circuit length required to establish an electrical connection with bond pads 19 of semiconductor device 12 (*see* FIGs. 2 and 3).

Please amend paragraph [0049] as follows:

[0049] Referring again to FIG. 7, a preferred embodiment of alignment device 40 also includes a mounting element engager 49. A preferred mounting element engager 49 includes two downward-facing slots 50 ~~and 51~~ and 53 formed in opposite ends of alignment device 40. Sides align a semiconductor device ~~12~~ package 10 (*see* FIG. 1) relative to the y-axis of alignment device 40. In the present embodiment, the ends of alignment device 40 align the semiconductor ~~device 12~~ device package 10 relative to the alignment device's X-axis. As will become apparent, alternative embodiments of mounting element engager 49 may be formed within interconnection receptacle 41, on carrier substrate 60, through the carrier substrate, or elsewhere upon or in proximity to alignment device 40.

Please amend paragraph [0050] as follows:

[0050] Mounting element engager 49 may include any other mechanism which will ~~support the~~ support semiconductor device package 10 (FIG. 1) and align the semiconductor device with respect to each of the alignment device's x-, y- and z-axes. FIG. 9 illustrates an

alignment device 40' having a variation 49' of the mounting element engager, which is formed in the front 56' and back 57' sides of alignment device 40'. Mounting element engager 49' is adapted to receive a corresponding mounting element 13" of the vertically mountable semiconductor device package, such as clips 24" and 28", described above in reference to FIG. 6b.

Please amend paragraph [0055] as follows:

[0055] FIG. 12 illustrates a computer 120 including a carrier substrate 122. Alignment device 40 attaches to carrier substrate 122. Vertically mountable semiconductor device package 10 is insertable into alignment device 40, which establishes an electrical connection between semiconductor device ~~12~~ package 10 (see FIG. 1) and carrier substrate 122. Thus, with the attachment of vertically mountable semiconductor device package 10 to carrier substrate 122, semiconductor device 12 is operatively incorporated into computer 120.